IPC ASSOCIATION CONN ELECTRONICS INDUS	© Copyright 2005.	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.			der both le	This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lower level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.								
752-21.1		IPC Web Site for Information on IPC-1752 Standard Form Typ http://www.ipc.org/IPC-175x Distribute				* Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materi				ials and Mfc Information				
upplier Info	ormation	,							,					
Company name*			Company unique ID			U	Unique ID Authority				Response Date*			
nsemi										2025-05-13				
Contact Name		Title - Contact			P	Phone - Contact*				Email - Contact*				
Product-Env-S	Stewards	Product Enviro Compliance			1	NA				Product-Env-Stewards@onsemi.com				
uthorized Rep	presentative*	Title - Representative			P	Phone - Representative*			Email - Representative*					
Product-Env-Stewards			Product Enviro Compliance			1	NA				Product-Env-Stewards@onsemi.com			
Requ	Requester Item Number M		Mfr Item Number Mfr Item Name			Effec		Version	М	anufacturing Site	7	Weight*	UOM	Unit Type
		FCD7N60TM SF1 600V 600mO		SF1 600V 600mOh	m E DPAK		2025-05-13	13 CPA		2	91.831	mg	Each	
	ing Process Informa		lamain al Daga	Allow	STD-020 MSL F	Datina	Pools Propo	ac Dody Tam		May Time at Dook	Tammanat	una Niversh	per of Reflow Cyc	alac
		Terminal Base Alloy J-STD-02 CU Alloy 1		S1D-020 MSL F	Kating	Peak Process Body Tempera 260 C		•				er of Reflow Cyc	cies	
•	te 1111 (Sn) - anneaied	C	O Alloy	1			200	<u> </u>	,	30	secon	ds 3		
omments	4:		J	20 1-										
	um time at peak temperat													
r more infort	mation regarding materia	I composition	piease refer t	o page 3										

RoHS Material Composition Declaration			Declaration Type *	Detailed							
Directive 2015/863/EU amending RoHS Directive 2011/65/EU											
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledges and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its paragraph. If the Company and the Supplier supplier have provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part, the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusivesource of the Supplier's Standard Terms and Conditions of Sale applicable to suc											
RoHS Declaration * 4 - Item(s) does not contain RoHS restricted substance	s per the definition above except for selected exemp	tions Supplier Acceptance	* Accepted							
Exemption: 7a: Lead in high melting temperature type solders (i.e. lead based solder alloys containing 85% by weight or more lead).											
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
Instructions: Complete all of the required fields on all pages of this form. Select the "Accepted" on the Supplier Acceptance drop-down. This will display the signature area. Digitally sign the declaration (if required by the Requester) and click on Submit Form to have the form returned to the Requester.											
Supplier Digital Signature Ra	astislav Drska	-En									

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	2.93	mg	Supplier	Silicon (Si)	7440-21-3		2.93	mg
Die Attach Solder	2.353	mg	Supplier	Silver (Ag)	7440-22-4		0.0588	mg
			A	Lead (Pb)	7439-92-1	7a	2.1765	mg
			Supplier	Tin (Sn)	7440-31-5		0.1176	mg
Lead Frame	150.208	mg	Supplier	Tin (Sn)	7440-31-5		0.16	mg
			В	Nickel (Ni)	7440-02-0		0.048	mg
			Supplier	Copper (Cu)	7440-50-8		150	mg
Mold Compound-Black	133.6	mg	Supplier	Phenol, polymer with 1,4-bis(methoxymethyl)benzene	26834-02-6		6.68	mg
			Supplier	Proprietary	Proprietary Data		6.012	mg
			Supplier	Ortho Cresol Novolac Resin	29690-82-2		6.68	mg
			Supplier	Carbon Black (C)	1333-86-4		0.668	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		113.56	mg
Plating	1.9	mg	Supplier	Tin (Sn)	7440-31-5		1.9	mg
Wire Bond - Al	0.84	mg	Supplier	Aluminum (Al)	7429-90-5		0.84	mg